

REMARKS

Applicants respectfully request consideration of the subject application as amended herein. This Amendment is submitted in response to the Office Action mailed March 22, 2005. Claims 4, 10-21, 39, 42-47, 49-55, 99-102 and 108-110 have been withdrawn. Claims 1-3, 5-9, 22, 37, 38, 40-41, 48, 56-60, 105-107 and 111 are rejected. In this Amendment, claims 5, 22, 37, 38, 56, and 111 have been amended and no new matter is added by this Amendment.

35 U.S.C. § 112, second paragraph

The Examiner has rejected claims 5, 6, 22, 38 and 56 under 35 U.S.C. § 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicants regard as the invention.

Claims 5, 6, and 56 contain the trademark/trade name NanoBlock™. The Examiner states that the trademark/trade name is used to identify/describe an integrated circuit, and accordingly, the identification/description is indefinite.

The Examiner has also rejected claims 22 and 58 for not clearly reciting the limitation “the substrate” as making reference to the first substrate and the second substrate.

Applicants have amended claims 5, 6, 22, 38 and 56 and respectfully submit that the amended claims comply with § 112, second paragraph, and therefore request withdrawal of this rejection.

Rejections under 35 U.S.C. § 102

Claims 1-2, 5-6, 27, 40-41, 48, 60, 105 and 111 are rejected under 35 U.S.C. §102(e) as being anticipated by WO 2001/62517 (Akita). Additionally, Claims 1, 7-9,

22, 37-38, 40, 48, 57-60, and 111 are rejected under 35 U.S.C. §102(e) as being anticipated by US 6,606,247 (Credelle).

Akita:

With respect to claims 1, 2, 3, 5, 6, and 105, Applicants respectfully submit that Akita did not anticipate these claims and at least did not disclose a thin-film dielectric layer formed over a portion of the IC and a portion of the first substrate as recited in the claims. The layer 36 that the Examiner refers to as a dielectric layer is not a dielectric layer and is an epoxy resin layer which does not function as a dielectric layer as can best be understood by the Applicants. If any insulation layer was used, Akita further used a passivation layer 22 which is ONLY formed over the chip 4 and the whole unit, the chip 4 and the layer 22 formed thereon is embedded within the substrate 10, which is then covered by the epoxy resin layer 36. Thus, Applicants submit that Akita did not disclose a thin-film dielectric layer formed over a portion of the IC and a portion of the first substrate as recited in the claims.

With respect to claims 37, 40, 48, and 60, similar to above, Akita did not anticipate these claims and at least did not disclose a thin-film dielectric layer formed over a portion of the IC and a portion of the first substrate as recited in the claims. The layer 36 that the Examiner refers to as a dielectric layer is not a dielectric layer and is an epoxy resin layer which does not function as a dielectric layer as can best be understood by the Applicants. If any insulation layer was used, Akita further used a passivation layer 22 which is ONLY formed over the chip 4 and the whole unit, the chip 4 and the layer 22 formed thereon is embedded within the substrate 10, which is then covered by the epoxy resin layer 36. Thus, Applicants submit that Akita did not disclose a thin-film dielectric layer formed over a portion of the IC and a portion of the first substrate as recited in the

claims.

Also, as above, claim 111 is also not anticipated for the same reason that Akita did not disclose a thin-film dielectric layer formed over a portion of the IC and a portion of the first substrate as recited in the claims.

Credelle:

Claims 1, 7-9, 22, 37-38, 40, 48, 57-60, and 111 are rejected under 35 U.S.C. §102(e) as being anticipated by Credelle.

Claims 1, 7-9, 22, 37-38, 40, 48, 57-60, and 111, as currently amended requires the conductive medium to be a conductive past. Credelle did not disclose such feature and as such, does not anticipate claim 1, 7-9, 22, 37-38, 40, 48, 57-60, and 111.

Accordingly, for at least the reasons submitted above, Applicants respectfully submit that Credelle does not anticipate the pending claims and earnestly request the Examiner to withdraw the subject rejections.

Rejections under 35 U.S.C. § 103

Claim 8 is rejected under 35 U.S.C. §103(a) as being unpatentable over Akita. Applicants respectfully submit that the pending claim 8 is patentable over Akita for the same reasons stated above. More particularly, Akita did not disclose a thin-film dielectric layer formed over a portion of the IC and a portion of the first substrate as recited in the claims.

Claim 107 is rejected under 35 U.S.C. §103(a) as being unpatentable over Akita in view of U.S 6,211,572 (Fjelstad). Applicants respectfully submit that the pending claim 8 is patentable over Akita for the same reasons stated above. More particularly,

Akita did not disclose a thin-film dielectric layer formed over a portion of the IC and a portion of the first substrate as recited in the claims.

Therefore, it would have not been obvious from the teaching of Akita to provide suggestion, motivation, or teaching of the elements of claims 8 and 107. As discussed above, Akita did not disclose a thin-film dielectric layer formed over a portion of the IC and a portion of the first substrate as recited in the claims. Therefore, combining Fjelstad to Akita would have not provided the elements of claim 107 or make obvious claim 107.

Accordingly, Applicants respectfully submit that the subject rejections be withdrawn.

CONCLUSION

Applicants respectfully submit that in view of the amendments and arguments set forth herein, the rejections herein have been overcome. Accordingly, it is believed that all claims now pending patentably define the subject invention over the prior art of record and are in condition for allowance and such action is earnestly solicited at the earliest possible date. If the Examiner determines the prompt allowance of these claims could be facilitated by a telephone conference, the Examiner is invited to contact Jim Scheller at (408) 720-8300.

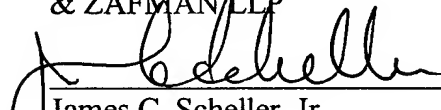
Deposit Account Authorization

Authorization is hereby given to charge our Deposit Account No. 02-2666 for any charges that may be due.

Respectfully submitted,

BLAKELY, SOKOLOFF, TAYLOR
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